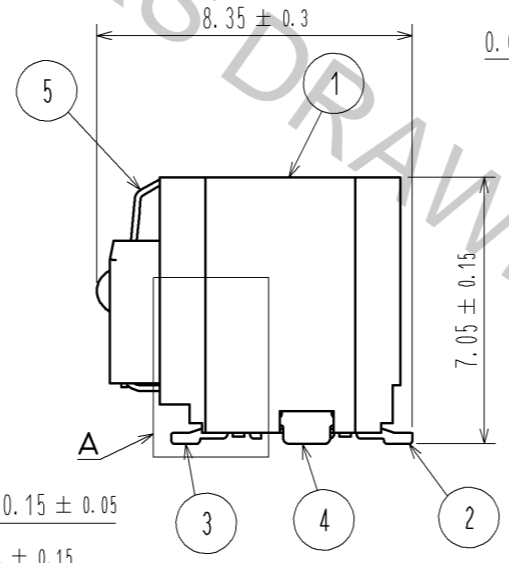
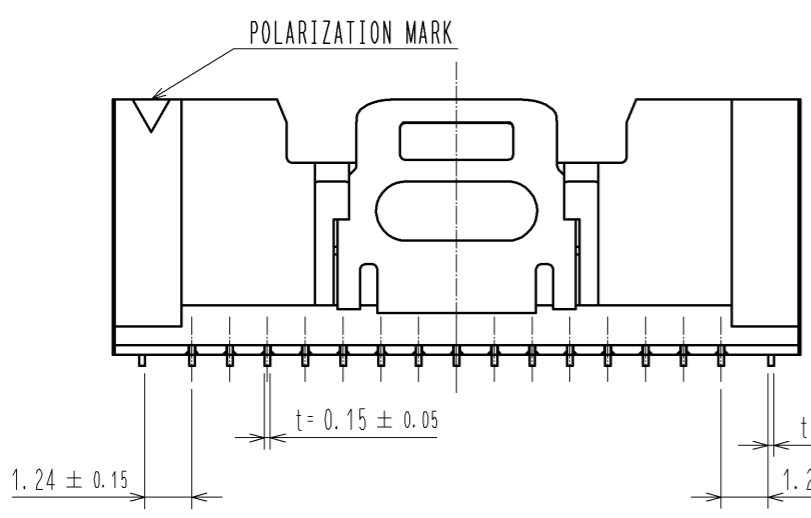
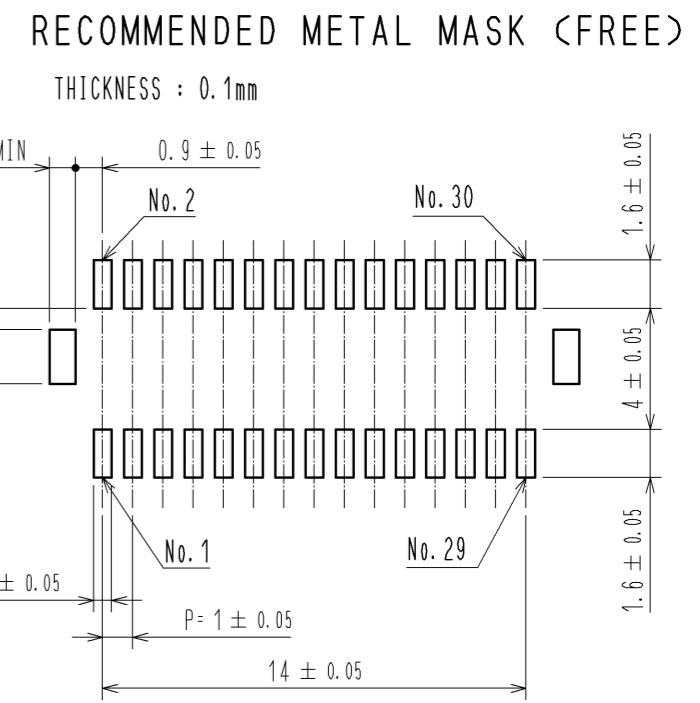
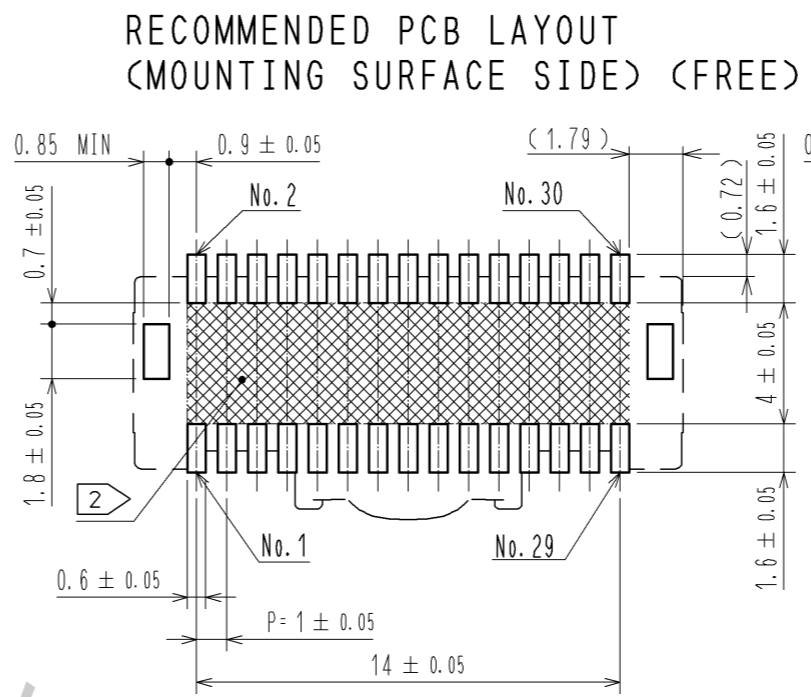
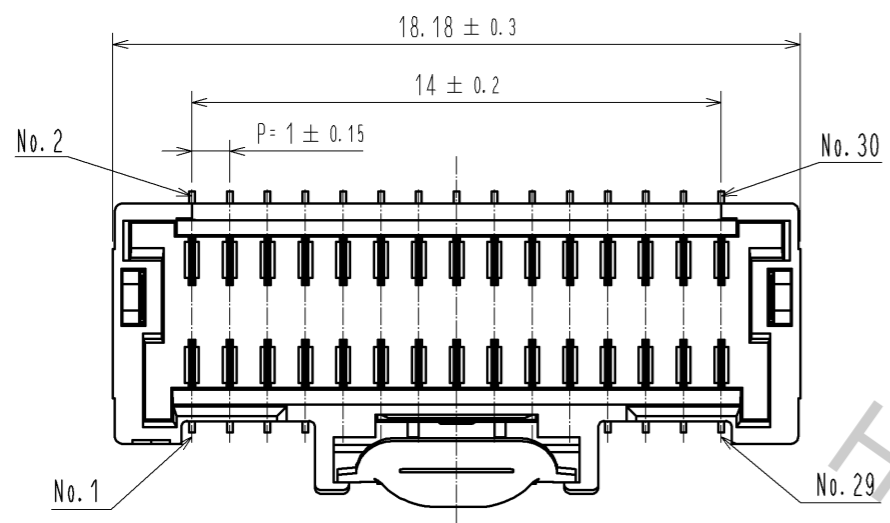
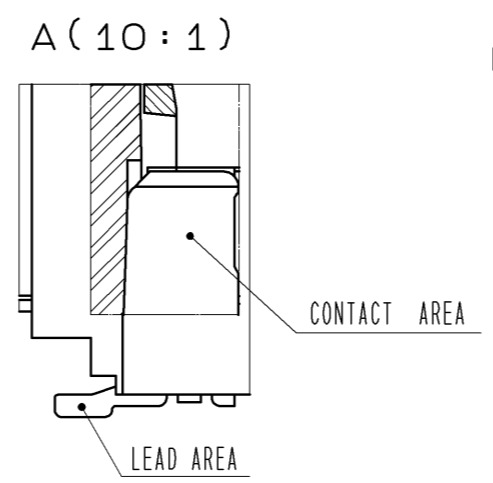
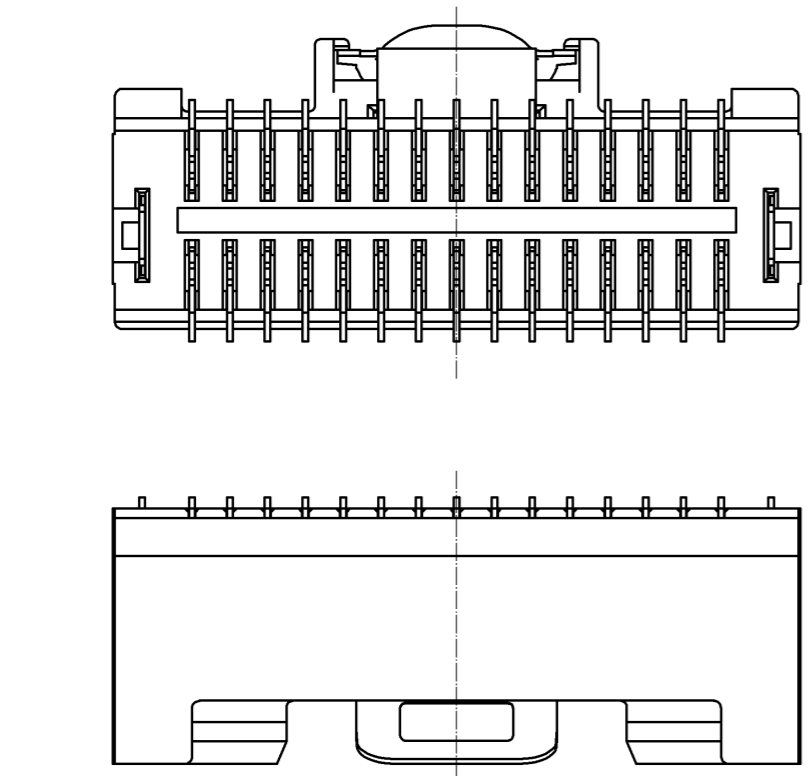
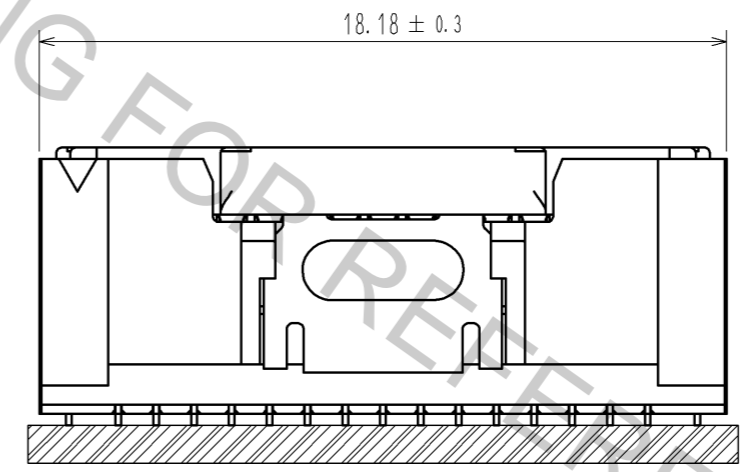


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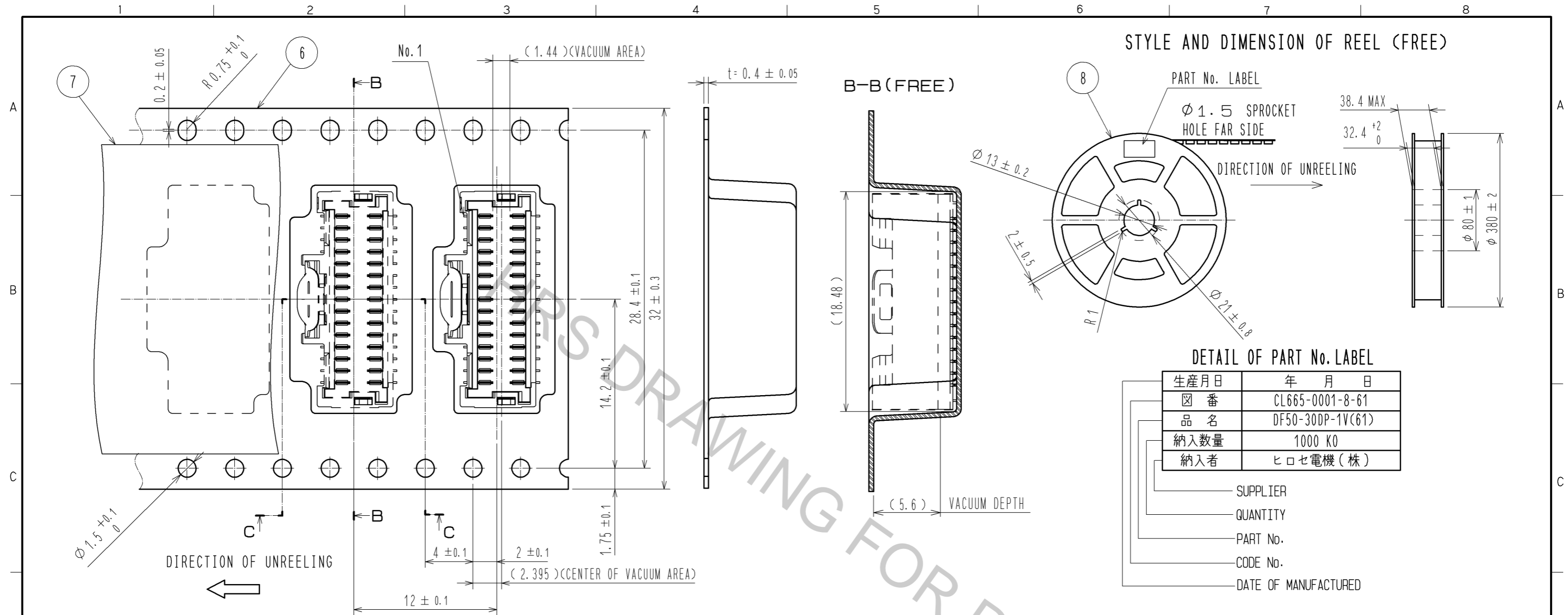
MATING FIGURE (5:1)



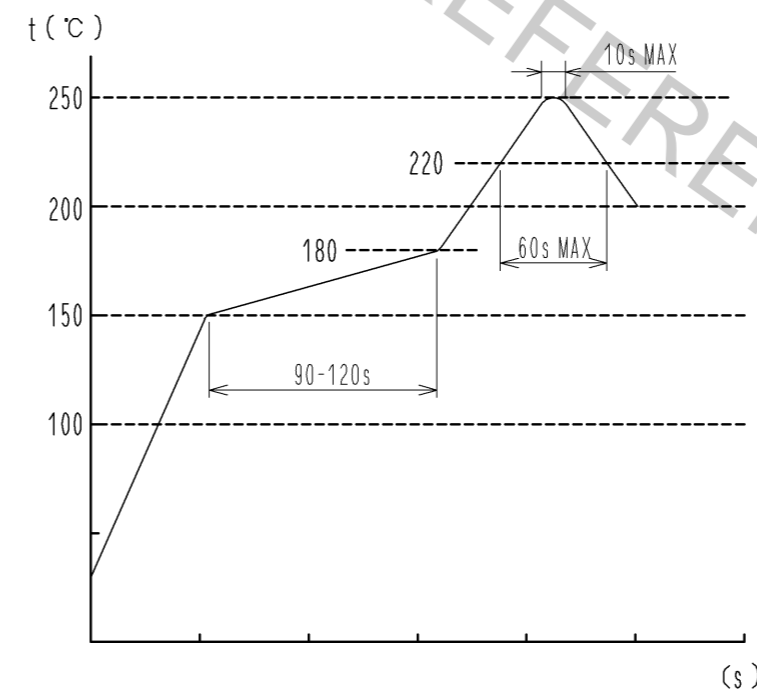
- NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX
 2. Hatched area indicated must be free of conductive traces or the conductive traces must be covered by resist film.
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

3	BRASS	CONTACT AREA : Au PLATING 0.05 μm MIN LEAD AREA : Au PLATING 0.05 μm MIN UNDER PLATING : Ni PLATING 1 μm MIN	8	PS	REEL , BLACK
2	BRASS	CONTACT AREA : Au PLATING 0.05 μm MIN LEAD AREA : Au PLATING 0.05 μm MIN UNDER PLATING : Ni PLATING 1 μm MIN	7	POLYESTER	CLEAR
1	LCP	NATURAL , UL94V-0	6	PS	CLEAR
			5	STAINLESS STEEL	—
			4	BRASS	CONTACT AREA : Sn PLATING 1 μm MIN UNDER PLATING : Ni PLATING 0.5 μm MIN
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS : mm		SCALE : FREE	COUNT : △		DESCRIPTION OF REVISIONS
DESIGNED		DESIGNED	DESIGNED	DESIGNED	DATE
CHECKED		CHECKED	DRAWING NO. : EDC3-320002-03		
DRAWN		DRAWN	PART NO. : DF50-30DP-1V(61)		
APPROVED		APPROVED	CODE NO. : CL665-0001-8-61		1/2

STYLE AND DIMENSION OF REEL (FREE)



REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES 2 CYCLES MAX.
THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART.

ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE,
PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT
THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF
MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION.
TEMPERATURE IS MEASURED AT CONTACT LEAD.

NOTES 4.1 REEL : 1000 CONNECTORS

5 REEL TO JIS C 0806. (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)

6. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

HRS	DRAWING NO.	EDC3-320002-03
	PART NO.	DF50-30DP-1V(61)
	CODE NO.	CL665-0001-8-61
		△ 2/2